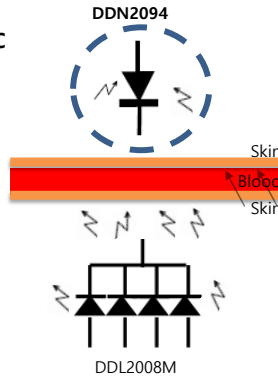
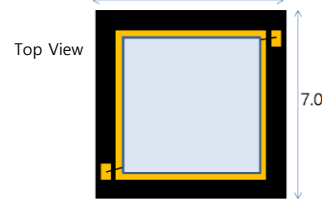


SCHEMATIC

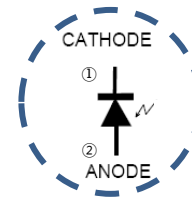
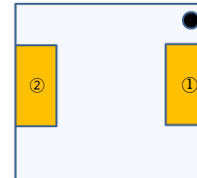


PACKAGE DIMENSION (mm)

w x h x t = 7.0 x 7.0 x 1.3
7.0



Bottom View



FEATURES

Chip on Board Mold Package
Optical Active Area = 4.66 x 4.66mm
Chip Size = 5.04 x 5.04mm

APPLICATIONS

Transmissive (Refractive) Sensing
Blood Analysis
Medical Device
Oximeter Probes

ABSOLUTE MAX. RATINGS (Ta=25°C unless otherwise noted)

SYMBOL	PARAMETER	MAX. RATED VALUE	UNITS
PD	Power Dissipation	120	mW
IF	Continuous Forward Current	50	mA
IFP	Peak Forward Current	100	mA
VR	Reverse Voltage	25	V
T stg	Storage Temp	-20 ~ +85	°C
T opr	Operating Temp	-20 ~ +80	°C
T sd	Soldering Temperature*1	240	°C

*Soldering time : t < 3s, **Moisture Sensivity Level 3

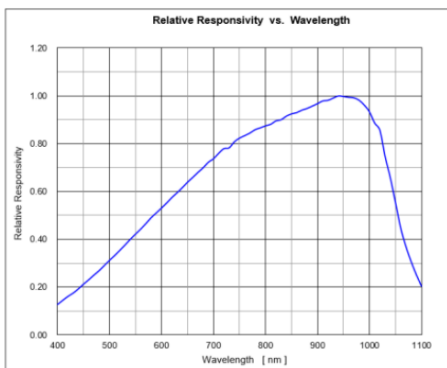
***Do not soldering on top pads, must soldering on only backside pads

****Do prebake 150°C 2HRs if reflow SMT

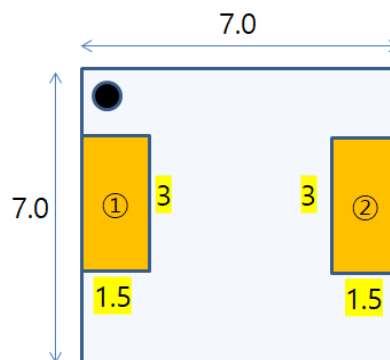
CHARACTERISTICS (Ta=25°C unless otherwise noted)

SYMBOL	CHARACTERISTIC	TEST CONDITION	MIN	TYP	MAX	UNITS
V BR	Reverse Breakdown Voltage	IR=100uA	60			V
I D	Reverse Dark Current	VR=10V			30	nA
I L	Light Current	5mW@940nm, VR=5V		215		uA
S	Spectral Response Range		400		1050	nm
CJ	Junction Capacitance	VR=5V, f=1MHz		49		pF
λ PEAK	Peak Wavelength			940		nm

Wavelength Characteristic



Footprint Top view (mm)



Packing Information



Anti Static vinyl bag

Label sticker

Recommend Reflow Soldering Profile

Prebake 150°C 2HRs if reflow SMT

Soldering 235°C within 10sec
Gradual cooling to avoid quenching

